



# P-Channel 60 V (D-S) MOSFET



PRODUCT SUMMARY					
V <sub>DS</sub> (V)	-60				
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS}$ = -10 V	0.0195				
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = -4.5 \text{ V}$	0.0250				
Q <sub>g</sub> typ. (nC)	76				
I <sub>D</sub> (A) <sup>a</sup>	-53				
Configuration	Single				

#### **FEATURES**

- TrenchFET® power MOSFET
- 100 % UIS tested

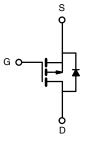




RoHS

#### **APPLICATIONS**

Load switch



P-Channel MOSFET

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	SUP53P06-20-E3

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>A</sub> = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		$V_{DS}$	-60	V	
Gate-source voltage		$V_{GS}$	± 20	v	
	T <sub>C</sub> = 25 °C		-53 <sup>a</sup>		
Continuous dusin suggest /T 150 °C\	T <sub>C</sub> = 70 °C	[	-46.8		
Continuous drain current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 25 °C	l <sub>D</sub>	9.2 <sup>b</sup>	A	
	T <sub>A</sub> = 70 °C	1 1	-8.1 <sup>b</sup>		
Pulsed drain current		I <sub>DM</sub>	-150		
Avalanche current pulse	L = 0.1 mH	I <sub>AS</sub>	-45		
Single pulse avalanche energy	L = 0.1 IIII	E <sub>AS</sub>	101	mJ	
Continuous source-drain diode current	T <sub>C</sub> = 25 °C		69 <sup>a</sup>	۸	
	T <sub>A</sub> = 25 °C	l <sub>S</sub>	2.1 <sup>b</sup>	Α	
	T <sub>C</sub> = 25 °C		104.2 <sup>a</sup>		
Maximum power dissipation	T <sub>C</sub> = 70 °C		66.7 <sup>a</sup>	W	
	T <sub>A</sub> = 25 °C	P <sub>D</sub>	3.1 <sup>b</sup>	VV	
	T <sub>A</sub> = 70 °C		2 b		
Operating junction and storage temperature range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT	
Maximum junction-to-ambient <sup>b</sup>	Steady state	R <sub>thJA</sub>	33	40	°C/W	
Maximum junction-to-case	Steady state	$R_{thJC}$	0.98	1.2	- C/W	

#### Notes

a. Based on  $T_C = 25\ ^{\circ}C$ 

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#### b. Surface mounted on 1" x 1" FR4 board

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	-60	-	-	V	
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	I 050 A	-	68	-	mV/°C	
V <sub>GS(th)</sub> temperature coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = -250 μA	=	-5.2	-	IIIV/ C	
Gate-source threshold voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = -250 \mu A$	-1	-	-3	V	
Gate-source leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA	
Zava gata valtaga dvain avyvent		V <sub>DS</sub> = -60 V, V <sub>GS</sub> = 0 V	-	-	-1	_	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = -60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C	-	-	-10	μA	
On-state drain current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = -5 V, V <sub>GS</sub> = -10 V	-120	-	-	Α	
Drain accuracy on state registeres 3	В	$V_{GS} = -10 \text{ V}, I_D = -30 \text{ A}$	-	0.0160	0.0195		
Drain-source on-state resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = -4.5 \text{ V}, I_D = -20 \text{ A}$	-	0.0200	0.0250	Ω	
Forward transconductance a	9 <sub>fs</sub>	$V_{DS} = -15 \text{ V}, I_D = -50 \text{ A}$	20	-	-	S	
Dynamic <sup>b</sup>							
Input capacitance	C <sub>iss</sub>		-	3500	-	pF	
Output capacitance	C <sub>oss</sub>	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	390	-		
Reverse transfer capacitance	C <sub>rss</sub>		=	290	-		
Total gata abayes	0	$V_{DS} = -30 \text{ V}, V_{GS} = -10 \text{ V}, I_D = -55 \text{ A}$	-	76	115	nC	
Total gate charge	Qg		-	38	60		
Gate-source charge	Q <sub>gs</sub>	$V_{DS} = -30 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -55 \text{ A}$	-	16	-		
Gate-drain charge	Q <sub>gd</sub>		-	19	-		
Gate resistance	R <sub>g</sub>	f = 1 MHz	-	5.2	-	Ω	
Turn-on delay time	t <sub>d(on)</sub>		-	10	15		
Rise time	t <sub>r</sub>	$V_{DD}$ = -2 V, $R_L$ = 2 $\Omega$	-	7	15		
Turn-off delay time	t <sub>d(off)</sub>	$I_D\cong$ -10 A, $V_{GEN}=$ -10 V, $R_g=$ 1 $\Omega$	-	70	110	ns	
Fall time	t <sub>f</sub>		-	40	60		
Drain-Source Body Diode Characteristic	cs						
Continuous source-drain diode current	I <sub>S</sub>	T <sub>C</sub> = 25 °C	-	-	-69	_	
Pulse diode forward current <sup>a</sup>	I <sub>SM</sub>	-		-	-150	Α	
Body diode voltage	V <sub>SD</sub>	I <sub>S</sub> = -30 A	-	-1	-1.5	V	
Body diode reverse recovery time	t <sub>rr</sub>		-	45	68	ns	
Body diode reverse recovery charge	Q <sub>rr</sub>	L 50 A di/dt 100 A/v. T 05 °C	-	59	120	nC	
Reverse recovery fall time	ta	$I_F = -50 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$	-	29	-		
Reverse recovery rise time	t <sub>b</sub>		-	16	-	ns	

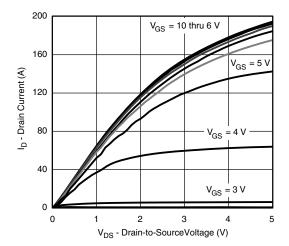
#### Notes

- a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %
- b. Guaranteed by design, not subject to production testing

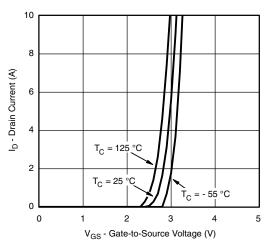
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



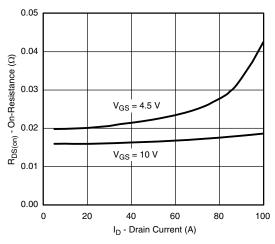
### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



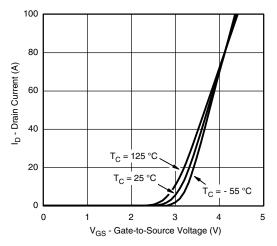
#### **Output Characteristics**



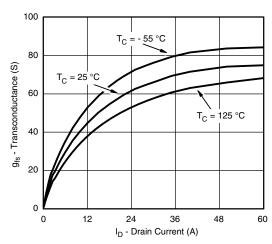
#### **Transfer Characteristics**



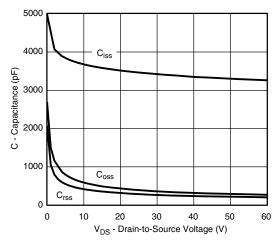
On-Resistance vs. Drain Current



#### **Transfer Characteristics**



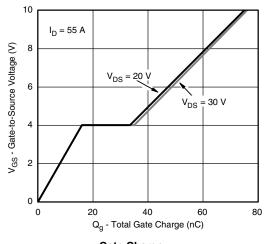
#### Transconductance



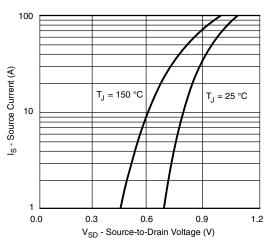
Capacitance



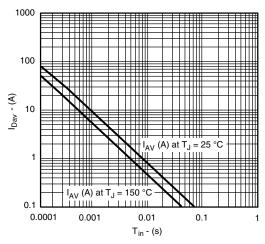
### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



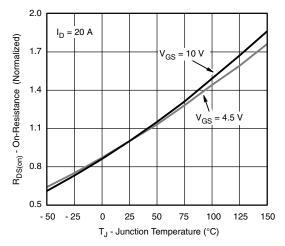




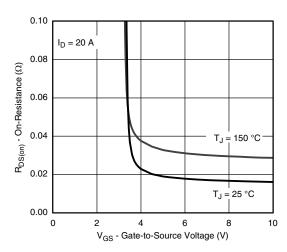
Source-Drain Diode Forward Voltage



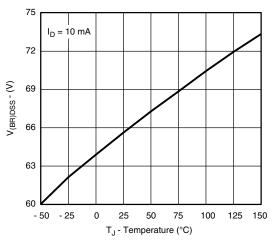
Single Pulse Avalanche Current Capability vs. Time



On-Resistance vs. Gate-to-Source Voltage



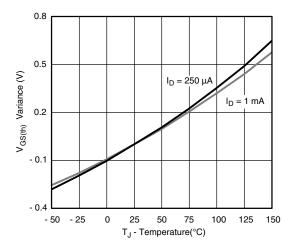
On-Resistance vs. Gate-to-Source Voltage



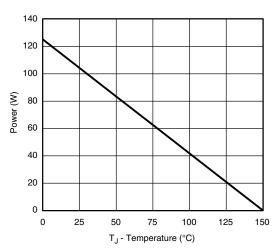
**Drain-Source Breakdown Voltage vs. Junction Temperature** 



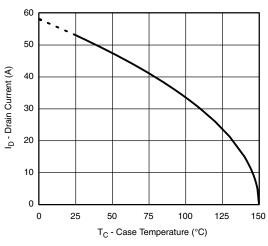
### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



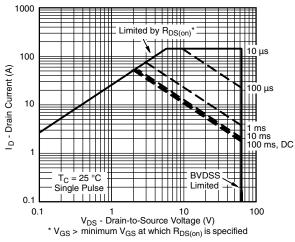
#### **Threshold Voltage**



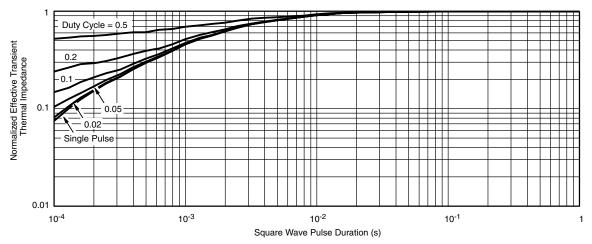
Power Derating, Junction-to-Case



Max. Drain Current vs. Case Temperature



Safe Operating Area, Junction-to-Case



#### Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg?68633">www.vishay.com/ppg?68633</a>.



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# **TO-220AB**



	D2

	MILLIMETERS		INCHES	
DIM.	MIN.	MAX.	MIN.	MAX.
А	4.25	4.65	0.167	0.183
b	0.69	1.01	0.027	0.040
b(1)	1.20	1.73	0.047	0.068
С	0.36	0.61	0.014	0.024
D	14.85	15.49	0.585	0.610
D2	12.19	12.70	0.480	0.500
Е	10.04	10.51	0.395	0.414
е	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.09	6.48	0.240	0.255
J(1)	2.41	2.92	0.095	0.115
L	13.35	14.02	0.526	0.552
L(1)	3.32	3.82	0.131	0.150
ØΡ	3.54	3.94	0.139	0.155
Q	2.60	3.00	0.102	0.118
ECN: T14-0413-Rev. P, 16-Jun-14 DWG: 5471				

#### Note

 $<sup>^{\</sup>star}$  M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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